



## PL135-27

Low Power, 1.62V to 3.63V, 10MHz to 40MHz, 1:2 Oscillator Fanout Buffer

Revision 2.0

### General Description

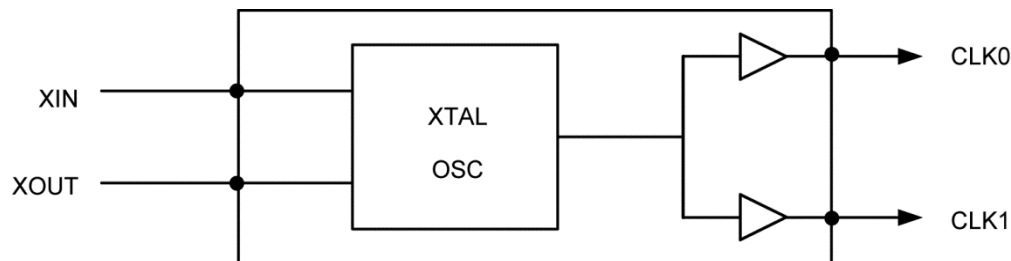
The PL135-27 is an advanced oscillator fanout buffer design for high performance, low-power, small form-factor applications. The PL135-27 accepts a fundamental crystal input of 10MHz to 40MHz and produces two LVCMOS outputs of the same frequency. The PL135-27 is designed to fit in a small 2mm × 1.3mm DFN package and offers the best phase noise, jitter performance and lowest power consumption of any comparable IC.

Datasheets and support documentation are available on Micrel's web site at: [www.micrel.com](http://www.micrel.com).

### Features

- Advanced oscillator design for wide frequency coverage
- Two LVCMOS outputs
- 8mA output drive strength
- Input/output frequency: 10MHz to 40MHz fundamental crystal
- Very low jitter and phase noise
- Low current consumption
- Single 1.62V to 3.63V power supply
- Available in 2.0mm × 1.3mm DFN-6L, GREEN/RoHS-compliant package

### Block Diagram



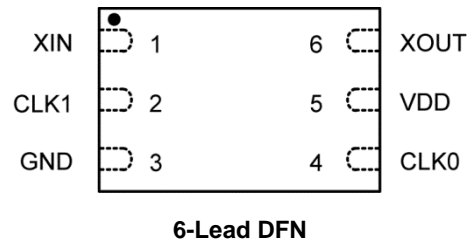
## Ordering Information

Part Number	Ambient Temperature Range	Marking <sup>(1)</sup>	Package
PL135-27GC-R	0°C to +70°C	J27	6-Pin 2.0mm x 1.3mm DFN
PL135-27GI-R	-40°C to +85°C	LLL	

**Note:**

1. LLL designates lot number.

## Pin Configuration



## Pin Description

Pin Number DFN-6L	Pin Name	Type	Pin Description
1	XIN	I	Crystal input
2	CLK1	O	Clock output
3	GND	P	GND connection
4	CLK0	O	Clock output
5	VDD	P	V <sub>DD</sub> connection
6	XOUT	O	Crystal output

**Absolute Maximum Ratings<sup>(2)</sup>**

Supply Voltage ( $V_{DD}$ ) ..... -0.5V to +4.6V  
 Output Voltage ( $V_{OUT}$ ) ..... -0.5V to  $V_{DD}+0.5V$   
 Storage Temperature ( $T_S$ ) ..... -65°C to +150°C

**Operating Ratings<sup>(3)</sup>**

Supply Voltage ( $V_{DD}$ ) ..... +1.62V to +3.63V  
 Ambient Temperature ( $T_A$ ) ..... -40°C to +85°C

**AC Electrical Characteristics**

$V_{DD} = 1.8V \pm 10\%$ ,  $2.5V \pm 10\%$  or  $3.3V \pm 10\%$ ;  $C_L = 15pF$ ;  $T_A = -40^\circ C$  to  $+85^\circ C$ , unless otherwise noted

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$F_X$	Crystal Input Frequency	Fundamental crystal	10		40	MHz
$t_{SETTLE}$	Settling Time	At Power-Up ( $V_{DD} \geq 1.62V$ )			2	ms
$dF/dV_{DD}$	$V_{DD}$ Sensitivity	Frequency vs. $V_{DD}$ , $\pm 10\%$	-0.5		0.5	ppm
$t_R$	Output Rise Time	10/90% $V_{DD}$ , $V_{DD}=3.3V$		2	3	ns
$t_F$	Output Fall Time	90/10% $V_{DD}$ , $V_{DD}=3.3V$		2	3	ns
$t_{SKEW}$	Output to Output Skew				500	ps
D-C	Duty Cycle		45	50	55	%

**Notes:**

- Exceeding the absolute maximum ratings may damage the device.
- The device is not guaranteed to function outside its operating ratings.

**DC Electrical Characteristics**

$V_{DD} = 1.8V \pm 10\%$ ,  $2.5V \pm 10\%$  or  $3.3V \pm 10\%$ ;  $C_L = 15pF$ ;  $T_A = -40^\circ C$  to  $+85^\circ C$ , unless otherwise noted

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{DD}$	Supply Current, Dynamic	$V_{DD} = 3.3V$ , 25MHz, No Load		1.6		mA
		$V_{DD} = 2.5V$ , 25MHz, No Load		1.2		mA
		$V_{DD} = 1.8V$ , 25MHz, No Load		0.9		mA
$V_{DD}$	Operating Voltage		1.62		3.63	V
$V_{OL}$	Output Low Voltage	$I_{OL} = +4mA$ , 3.3V			0.4	V
$V_{OH}$	Output High Voltage	$I_{OH} = -4mA$ , 3.3V	2.4			V
$I_{OSD}$	Output Current	$V_{OL} = 0.4V$ , $V_{OH} = 2.4V$	8			mA

**Crystal Specifications**

$V_{DD} = 1.8V \pm 10\%$ ,  $2.5V \pm 10\%$  or  $3.3V \pm 10\%$ ;  $C_L = 15pF$ ;  $T_A = -40^\circ C$  to  $+85^\circ C$ , unless otherwise noted

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$F_{XIN}$	Fundamental Crystal Resonator Frequency		10		40	MHz
$C_{L(xtal)}$	Crystal Loading Rating			12		pF
$P_D$	Operating Drive Level			0.1	2	mW
$C_0$	Shunt Capacitance				5.5	pF
ESR	Effective Series Resistance	$C_0 \leq 5.5pF$			40	$\Omega$
		$C_0 \leq 2.5pF$			60	$\Omega$

## Layout Recommendations

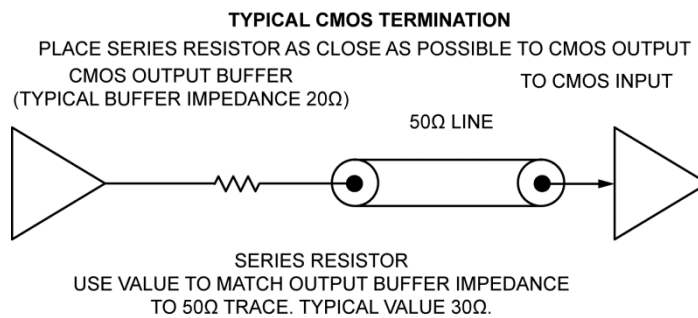
The following guidelines are to assist you with a performance optimized PCB design:

### Signal Integrity and Termination Considerations

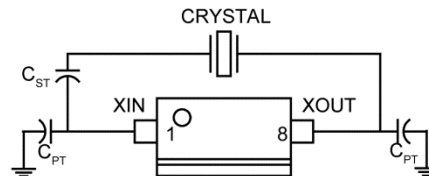
- Keep traces short.
- Trace = Inductor. With a capacitive load this equals ringing.
- Long trace = Transmission Line. Without proper termination this will cause reflections (looks like ringing).
- Design long traces as “striplines” or “microstrips” with defined impedance.
- Match trace at one side to avoid reflections bouncing back and forth.

### Decoupling and Power Supply Considerations

- Place decoupling capacitors as close as possible to the VDD pin(s) to limit noise from the power supply
- Multiple VDD pins should be decoupled separately for best performance.
- Addition of a ferrite bead in series with VDD can help prevent noise from other board sources
- Value of decoupling capacitor is frequency dependent. Typical value to use is 0.1 $\mu$ F.



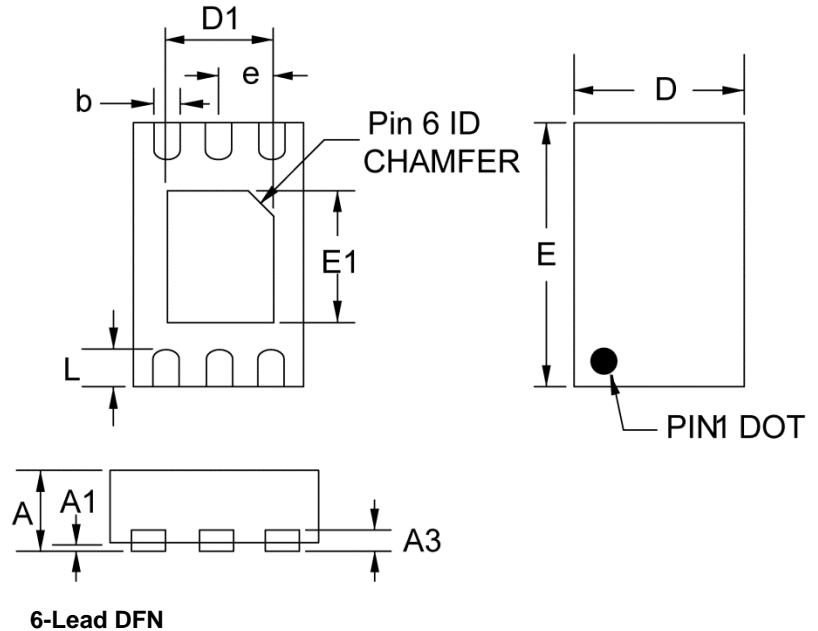
**CRYSTAL TUNING CIRCUIT**  
SERIES AND PARALLEL CAPACITORS USED TO FINE TUNE THE CRYSTAL LOAD TO THE CIRCUIT LOAD



CST – SERIES CAPACITOR, USED TO LOWER CIRCUIT LOAD TO MATCH CRYSTAL LOAD. RAISES FREQUENCY OFFSET. THIS CAN BE ELIMINATED BY USING A CRYSTAL WITH A CLOAD OF EQUAL OR GREATER VALUE THAN THE OSCILLATOR.  
CPT – PARALLEL CAPACITORS, USED TO RAISE THE CIRCUIT LOAD TO MATCH THE CRYSTAL LOAD. LOWERS FREQUENCY OFFSET.

## Package Information<sup>(4)</sup>

Symbol	Dimension in MM	
	Min.	Max.
A	0.45	0.60
A1	0.00	0.05
A3	0.152	0.152
b	0.15	0.25
e	0.40BSC	
D	1.25	1.35
E	1.95	2.05
D1	0.75	0.85
E1	0.95	1.05
L	0.20	0.30



### Note:

4. Package information is correct as of the publication date. For updates and most current information, go to [www.micrel.com](http://www.micrel.com).

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